



Revision History

Revision	Notes
A	*** PRELIMINARY ***
B	tuned loop and added RC snubber

NOTES:

- 1) R3 for test purposes only
- 2) built on PCB PMP10088 RevA
- 3) ref des > 100 placed externally

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Number: PMP10090 Rev: B
 SVN Rev: Not in version control
 Drawn By:
 Engineer: B.Geck

Designed for: Public Release Mod. Date: 10/8/2014
 Project Title: inverting BuckBoost w/ dual output
 Sheet Title:
 Assembly Variant: Variant name not interpreted Sheet: 1 of 1
 File: PMP10090RevB.SchDoc Size: A4
 Contact: <http://www.ti.com/support>

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